

# Infineon Linux Wi-Fi CYW5551x (Firmware) release notes

# **About this document**

## **Scope and purpose**

Thank you for your interest in Infineon's Linux Wi-Fi Software Release. This document provides an overview of the bug fixes and known issues for the AIROC™ CYW5551x Wi-Fi chips on the current release for Linux.

Intended audience

This document is intended for anyone who uses the Infineon AIROC™ CYW5551X Wi-Fi chips on a Linux host.

# Infineon Linux Wi-Fi driver (FMAC) (v2025\_0219) release notes



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# 1 Overview

# 1.1 High-level summary

This document details the bug fixes for CYW5551x on the software release.

This software release includes the following:

- Firmware and Clm blob
  - ifx-Linux-firmware GitHub page

## 1.2 Device firmware revision details

#### Table 1 Firmware revision details

Device	Wi-Fi firmware version	
CYW5551X	SDIO	28.10.387.16

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# 2 Description of firmware changes – CYW5551X

## **Bug fixes**

Fixes the carrier sense issue in JP regulatory.

#### **NVRAM update**

Contact the module vendor or local Infineon distribution channel (FAE or local sales representative) to get the latest NVRAM update.

#### **Known issues**

- Combo COEX notice UDP low throughput during BLE CIS and Wi-Fi co-ex scenario
- Third party COEX low Zigbee performance noticed Wi-Fi Rx throughput scenario

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